

In the Claims:

Please cancel claim 3. The claims are as follows:

1. (Previously presented) A security enclosure, comprising:
 - an electronic assembly;
 - a tamper respondent wrap secured at least partially around the assembly, wherein the tamper respondent wrap comprises a plurality of layers, and wherein a plurality of electrically conductive lines or a plurality of electrically conductive ink traces exist inside each layer of the wrap; and
 - an extension cable electrically connecting the wrap to the assembly.
2. (Previously presented) The security enclosure of claim 1, wherein the electronic assembly comprises a cryptographic processor card adapted to store key codes to encrypt and decrypt information enclosed within the electronic assembly.
3. (Cancelled)
4. (Original) The security enclosure of claim 1, wherein the tamper respondent wrap further includes a plurality of bonding pads formed at a first end of the wrap.
5. (Original) The security enclosure of claim 4, wherein the tamper respondent wrap further includes a system of resistors within each layer of the wrap.

6. (Previously presented) The security enclosure of claim 5, wherein each layer of the wrap comprises the ink traces, and wherein the system of resistors connect the ink traces within each layer of the wrap to the bonding pads.

7. (Original) The security enclosure of claim 1, wherein the extension cable further includes a plurality of interconnections at a first end of the extension cable.

8. (Original) The security enclosure of claim 7, wherein the extension cable further includes a plurality of bonding pads at a second end of the extension cable.

9. (Original) The security enclosure of claim 8, wherein wires connect the interconnections and the bonding pads of the extension cable.

10. (Previously presented) The security enclosure of claim 1, wherein a bonding pad on the wrap is bonded to a bonding pad on the extension cable, wherein an entire first surface of the bonding pad on the extension cable is in direct mechanical contact with the extension cable at a contact surface portion of the extension cable, wherein an entire first surface of the bonding pad on the wrap is in direct mechanical contact with the wrap at a contact surface portion of the wrap, wherein the contact surface portion of the extension cable is aligned directly above the entire first surface of the bonding pad on the extension cable, the entire first surface of the bonding pad on the wrap, and the contact surface portion of the wrap.

11. (Cancelled)

12. (Original) The security enclosure of claim 1, wherein the wrap at least partially covers the extension cable.

13. (Previously presented) The security enclosure of claim 1, wherein the extension cable comprises a flexible dielectric material.

14. (Previously presented) A security enclosure, comprising:

an electronic assembly;

an extension, having a first end inserted in the assembly, and a second end having at least one bonding pad thereon; and

a tamper respondent wrap at least partially surrounding the assembly, having at least one corresponding bonding pad, wherein the bonding pad of the extension is secured to the bonding pad of the wrap, wherein an entire first surface of the bonding pad of the extension is in direct mechanical contact with the extension at a contact surface portion of the extension, wherein an entire first surface of the bonding pad of the wrap is in direct mechanical contact with the wrap at a contact surface portion of the wrap, wherein the contact surface portion of the extension is aligned directly above the entire first surface of the bonding pad of the extension, the entire first surface of the bonding pad of the wrap, and the contact surface portion of the wrap, wherein the tamper respondent wrap comprises a plurality of layers, and wherein each layer of the wrap includes a plurality of electrically conductive lines or a plurality of electrically conductive ink

traces.

15. (Original) The security enclosure of claim 14, wherein the first end of the extension comprises at least one interconnection which forms an electrical connection between the assembly and the extension.

16. (Original) The security enclosure of claim 15, wherein the at least one interconnection is electrically connected to the at least one bonding pad of the extension via a wire.

17. (Previously presented) The security enclosure of claim 14, wherein each layer of the wrap includes, inside said each layer of the wrap, the plurality of electrically conductive lines or the plurality of electrically conductive ink traces.

18. (Previously presented) The security enclosure of claim 14, wherein each layer of the wrap comprises the ink traces, and wherein the wrap further includes a system of resistors connecting the ink traces within the wrap to the bonding pads of the wrap.

19. (Original) The security enclosure of claim 14, wherein the extension comprises a flexible cable.

20. (Previously presented) A security enclosure, comprising:
an electronic assembly; and

a tamper respondent wrap electrically connected to the assembly via an attachable extension, wherein the tamper respondent wrap comprises a plurality of layers, and a plurality of electrically conductive lines or a plurality of electrically conductive ink traces exist inside each layer of the wrap.

21. (Previously presented) A security enclosure, comprising:

an electronic assembly; and
a tamper respondent wrap electrically connected to the assembly via an attachable extension, wherein the attachable extension comprises a flexible extension cable, and wherein an end of the flexible extension cable has a bonding pad thereon, wherein the tamper respondent wrap comprises a bonding pad formed on an end thereon, wherein the bonding pad of the extension cable is secured to the bonding pad of the wrap, wherein an entire first surface of the bonding pad of the extension cable is in direct mechanical contact with the extension cable at a contact surface portion of the extension cable, wherein an entire first surface of the bonding pad of the wrap is in direct mechanical contact with the wrap at a contact surface portion of the wrap, wherein the contact surface portion of the extension cable is aligned directly above the entire first surface of the bonding pad of the extension cable, the entire first surface of the bonding pad of the wrap, and the contact surface portion of the wrap.

22-24. (Cancelled)

25. (Previously presented) The security enclosure of claim 21, wherein the extension further

comprises a plurality of interconnections formed at a second end of the extension.

26. (Previously presented) The security enclosure of claim 21, wherein each layer of the wrap comprises, within said each layer of the wrap, ink traces, and wherein a system of resistors electrically connects the bonding pads of the wrap to the ink traces of the wrap.

27-30. (Cancelled)

31. (Previously presented) A method of forming a security enclosure, comprising:
providing an electronic assembly having an opening therein;
inserting a first end of an extension within the opening of the assembly;
wrapping a tamper respondent wrap at least partially around the assembly, wherein the tamper respondent wrap comprises a plurality of layers, and wherein a plurality of electrically conductive lines or a plurality of electrically conductive ink traces exist inside each layer of the wrap; and
electrically connecting a second end of the extension to the wrap.

32. (Previously presented) The method of claim 31, wherein the tamper respondent wrap includes an adhesive inner surface that adheres the wrap to the electronic assembly.

33. (Previously presented) The method of claim 31, wherein the extension comprises a flexible extension cable, wherein the tamper respondent wrap comprises a bonding pad formed on an end thereof, wherein the bonding pad of the extension cable is secured to the bonding pad of the

wrap, wherein an entire first surface of the bonding pad of the extension cable is in direct mechanical contact with the extension cable at a contact surface portion of the extension cable, wherein an entire first surface of the bonding pad of the wrap is in direct mechanical contact with the wrap at a contact surface portion of the wrap, wherein the contact surface portion of the extension cable is aligned directly above the entire first surface of the bonding pad of the extension cable, the entire first surface of the bonding pad of the wrap, and the contact surface portion of the wrap.

34. (Previously presented) The security enclosure of claim 20, wherein the tamper respondent wrap includes an adhesive inner surface that adheres the wrap to the electronic assembly.

35. (Previously presented) The security enclosure of claim 20, wherein each layer of the wrap comprises the electrically conductive lines, and wherein the electrically conductive lines include an electrically conductive thermoplastic polymer.

36. (Previously presented) The security enclosure of claim 20, wherein each layer of the wrap comprises the electrically conductive lines, and wherein the electrically conductive lines include an electrically conductive thermoset polymer.